Customer Information Notification

202105013I : NXP Standardized Tray Attributes for BGA 17x17 Bulk Shipments

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 29, 2021 **Effective date:**Oct 29, 2021

Change Category

☐ Wafer Fab Process
☐ Assembly Process
☐ Product Marking
☐ Test Process
☐ Design
☐ Wafer Fab Materials
☐ Assembly Materials
☐ Mechanical Specification
☐ Test Equipment
☐ Errata
☐ Wafer Fab Location
☐ Assembly Location
☑ Packing/Shipping/Labeling
☐ Test Location
☐ Electrical spec./Test coverage
☐ Firmware
☐ Other

PCN Overview

Description

NXP Semiconductors announces a Standardized Tray Supplier Initiative, for the tray configuration bulk shipments of BGA 17x17 devices associated with this notification. The new tray initiative results in standardized tray attributes, by package size, to allow manufacturing consolidation and avoid different tray vendor mixture issues for customers. This standardized tray initiative can be rolled out across different NXP package types/sizes as future opportunities present.

** No change to tray critical dimensions **

Minor change only to tray attributes, including:
- End Tab Embossment: Change from Peak to NXP logo
- Tray Temperature: Meet or exceed current tray value
- Color Stripe: Change from no stripe to white color stripe

Even though no change to tray critical dimensions, Customer Information Notification 202105013I is issued to ensure no customer manufacturing disruption upon NXP implementation of new standardized tray for BGA 17x17 devices purchased in bulk tray configuration from NXP. Upon notification Effective Date, BGA 17x17 products will begin a ramped implementation shipment to customers with new tray attributes.

Please Note: During standardized tray ramped introduction, it is recommended to not mix or stack different tray types.

Please see attached information for tray change details.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PS-03

Reason

New standardized tray, by package size, to allow manufacturing consolidation, and avoid different tray vendor mixture issues for customers of NXP tray product shipments.

Identification of Affected Products

Product identification does not change
No change to NXP orderable part number / 12NC.
Minor change only to tray attributes - see attached information for tray change details.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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